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To suit the scope of the journal and the size of the letter, it is expected that contributions will describe the context of the work and contain novel content, the validity of which can be neatly provided in a concise paper. For example, a letter could address a specific aspect dealt with in a wider study, which is worth being published on its own, or alternatively new ideas, whose validity can be clearly envisaged through an initial scientifically sound study, which may be further developed afterwards. Another possibility is a synthesis of already published studies, whose results have required further elaboration to provide new findings and understanding. Given these possibilities, letters can cover a very wide range of topics in geotechnical engineering. In all cases it is important that the content is set in the proper background context and the letters contain sufficient information for the readers to critically review the conclusions.

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Authors: M. G. Lee, J. G. Ha, S. B. Jo, H. J. Park, and D. S. Kim

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Authors: J. G. Tom, C. D. O'Loughlin, D. J. White, A. Haghghi, and A. Maconochie

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Authors: C.E. Choi, G.R. Goodwin, C.W.W. Ng, D.K.H. Cheung, J.S.H. Kwan, and W.K. Pun

5. [The inter-scale behaviour of two natural scaly clays](#) (Volume 6 Issue 3, September, 2016)

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